

TECHNICAL SPECIFICATION	ENAVISION 800-QUAD-P
OVERVIEW	
Build Envelop Volume (mm ³) Range of Layer Thickness Feature Thickness Laser Type Laser Power Scanning Speed Scanning System Electrical Connection (Voltage) Electrical Connection (Current) Inert Gas O2 Level Vacuum Pump Operating System Network Build Plate Temperature Build chamber gas volume	800X800X500 mm (31,50 x 31,50 x19,68 in) 20-100 µm (0,0007 - 0,004 in) 150 µm Fiber laser 1000 W (Single Mode) x 4 Up to 11 m/S (433,07 in) 3D dynamic focused scanning system x 4 480 V, 3 PH, 60 Hz 50 A Argon / Nitrogen <100 ppm Yes Windows 10 / X Ethernet / Ethercat 0- 200 °C 262.5 to 1050 m3/h
OPTICAL SCANNING SYSTEM	
Scanning Speed Scanning System Cooling System	Up to 11 m/S (433,07 in) 3D dynamic focused scanning system x 4 Water
CONTROL UNIT	
Ccontrol System Processor Operating System HMI PLC Motion Control	Beckhoff Industrial PC Intel i5-i7 Windows 10 / X 21.5 in, touch operated TwinCat 3 TwinCat 3 NC PTP
SOFTWARE	
Data Preparation Software Data Processing Software Supported File Types	Materiliase Magics and Modules Ermaksan Build Processor STL , 3MF, AMF,, DAE , FBX, VRML ...
FEATURES	
Beam Focus Diameter/Beam Diameter Beam Correction Recoater Blade Typical Dimensional Accuracy Surface roughness Relative Density of as Printed Parts Process Monitoring Camera Quality Comformation	85 -150 µm Auto Silicon ± 200 µm Ra<20µm ≥99% HD Camera to follow the building process CE

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